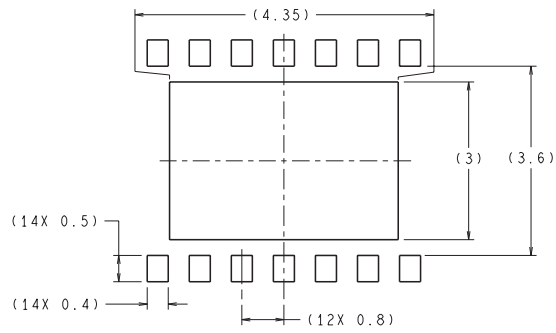
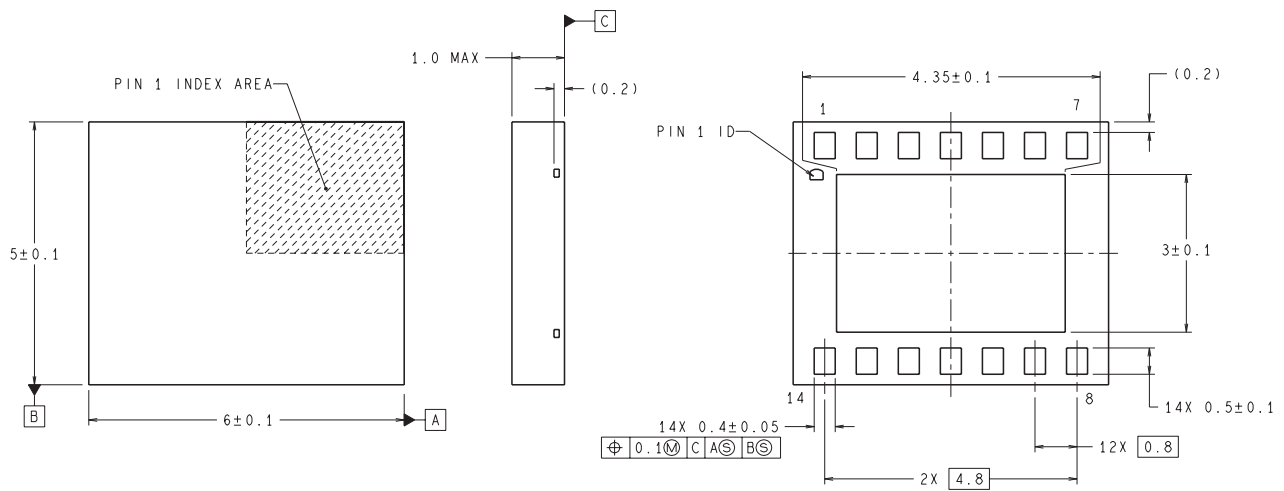


NHH0014A



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS



LDC14A (REV A)

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